**Etan Bennett**

196 Barclay Square Drive, Rochester NY|Email:ebennett@stevens.edu|GoogleVoice:+15856660191|etanbennett.weebly.com

**Objective:** To obtain a full time Electrical Engineering position

**Education:** **Stevens Institute of Technology,** Hoboken, New Jersey

Master of Engineering in Systems Engineering, expected 2016 GPA: 3.5

Bachelor of Engineering in Electrical Engineering, expected 2016 GPA: 3.7

**Honors:** E.A. Stevens Scholarship, Presidential Scholarship, D. Performing Arts Scholarship, Dean’s List, President’s List

**Coursework:** Wireless Systems, Autonomous Mobile Robots, Project Management of Complex Systems, System Supportability and Logistics

**Skills: Hardware:** PC based systems, PLCs, Rockwell Systems, Basic Linux, TI Embedded Development

**Software:** C/C++, LabVIEW, MatLab, RSLogix 5000, SolidWorks, Autodesk AutoCAD, Microsoft Office, Minitab, Cadence: PSpice/OrCAD/Allegro, ROS Hydro, Altium, Multisim

**Lab:** Oscilloscope circuit analysis, dynamic signal analysis, digital multimeter, optical microscopy, soldering, woodworking, metalworking, wiring, short circuit troubleshooting, scanning electron and focused ion beam microscopy, laser scanning microscopy, thermography

**Work** **Getinge Group: Maquet Cardiopulmonary,** Rastatt, Germany

**Experience:** Co-op Hardware Design: June-December 2015

* Developed a Bluetooth Low Energy auxiliary sensor device for a life support system
* Documented the design process including: Functional Requirements, Risk Analysis, and HW Specification
* Prototyped the functional HW design to integrate SW architecture and communications
* Designed PCB Layout for Prototyping
* Resolved PCB malfunction through circuit analysis

**The Aerospace Corporation: Electronic Materials and Devices,** El Segundo, California

Co-op Failure Analysis: May-August 2014

* Expanded methods to measure the electrical properties of devices and nanoscale materials
* Determined capacitance and bias voltage measurements of PIN photodiodes to measure depletion width
* Prepared samples for SEM analysis and FIB milling
* Refined LSM tile scanning procedure to fully image devices at 100x resolution
* Coded lock-in thermography of device defects with LabVIEW, using an infrared imaging camera

**Getinge Group: Maquet Cardiac Assist,** Mahwah, New Jersey

Co-op PCBA Testing: January-May 2014

* Assisted Electrical Engineers with the testing and documentation of printed circuit board assemblies
* Constructed and tested PCB breadboards to test system sensor modules
* Assembled system test devices for use in product verification
* Updated engineering drawings to account for system design changes
* Purchased components for the construction of development equipment, tools and test fixtures
* Wrote engineering specifications and manufacturing functionality test documents

**General Motors: GM Component Holdings LLC,** Rochester, New York

Co-op Quality Process: September-December 2012

* Created an Excel macro to facilitate collection and analysis of test stand data
* Experimented with different part deformations to fail a test and create a setup verifier
* Managed lot traceability and quality documents for management to understand part rejection
* Supervised part trails to control flow of samples through the manufacturing process
* Reviewed machine operation to certify that requested functions met plant qualifications

Co-op Electrical Controls: May-August 2012

* Supported Gen V Fuel Injector line installation and operation
* Standardized touchscreen interfaces to promote operator ease of use
* Programmed guard door, reject tray and conveyor operation using ladder logic
* Placed maintenance calls for skilled labor to assist in resolving improper machine functions
* Analyzed online code to clarify machine faults and continue production

**Activities:** Volleyball, knitting, sailing, biking, pole vaulting, jazz saxophone, travel, Sigma Nu International Fraternity